

FQA90N15_F109-VB Datasheet N-Channel 150V (D-S) MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
150	0.017 at V _{GS} = 10 V	90 ^a		

FEATURES

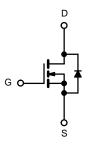
- Trench Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested



APPLICATIONS

• Isolated DC/DC Converters





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	150	V
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	1-	90 ^a	
Continuous Diam Current (1) = 173 C)	T _C = 125 °C	I _D	75 ^a	
Pulsed Drain Current		I _{DM}	250	_ A
Avalanche Current	L = 0.1 mH	I _{AS}	35	
Single Pulse Avalanche Energy ^b	L=0.11IIII	E _{AS}	61	mJ
Maximum Power Dissipation ^b	T _C = 25 °C	D D	375 ^c	10/
	T _A = 25 °C ^d	$ P_{D}$ $-$	3.75	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.4		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).

服务热线:400-655-8788



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	150			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		4		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = 100 V, V _{GS} = 0 V			1		
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μA	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 30 A		0.017			
	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.023		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.034			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•			•			
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		5100		pF	
Output Capacitance	C _{oss}			480			
Reverse Transfer Capacitance	C _{rss}			210			
Total Gate Charge ^c	Qg			90	130	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 65 \text{ A}$		23			
Gate-Drain Charge ^c	Q_{gd}			34			
Gate Resistance	R _g		0.5	1.7	3.3	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35	- ns	
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_L = 1.5 \Omega$ $I_D \cong 65 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		220	330		
Turn-Off Delay Time ^c	t _{d(off)}			45	70		
Fall Time ^c	t _f			200	300		
Source-Drain Diode Ratings and Cha	aracteristics 7	T _C = 25 °C ^b					
Continuous Current	I _S				65	^	
Pulsed Current	I _{SM}				140	- A	
Forward Voltage ^a	V _{SD}	I _F = 65 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/μs		8	12	Α	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	иC	

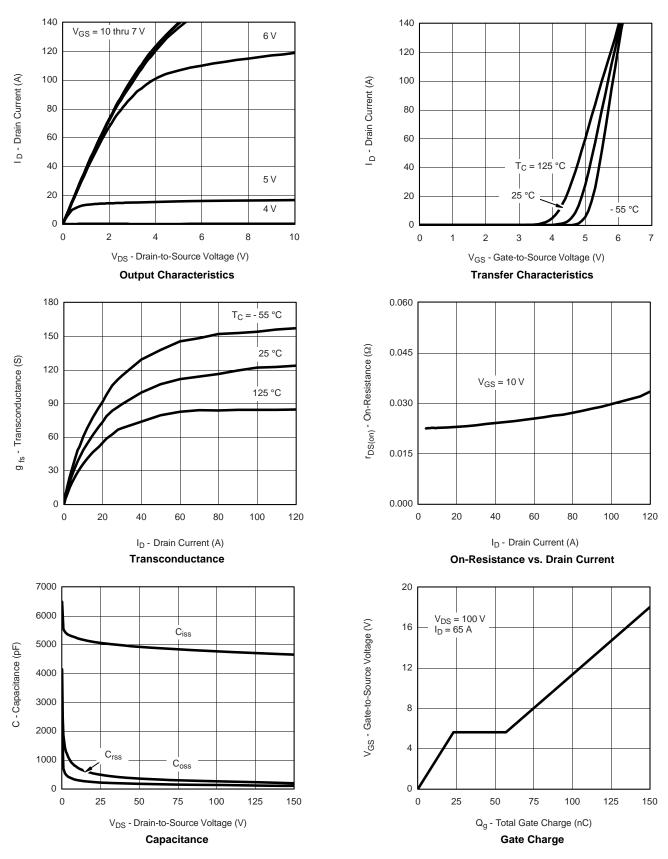
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

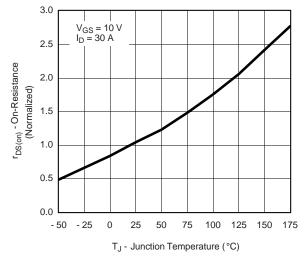


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

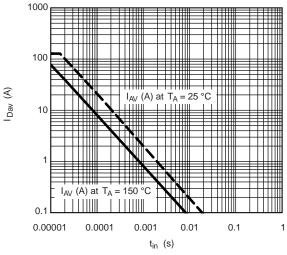




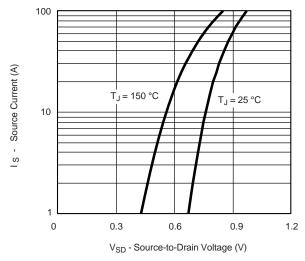
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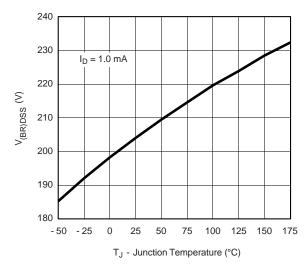
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



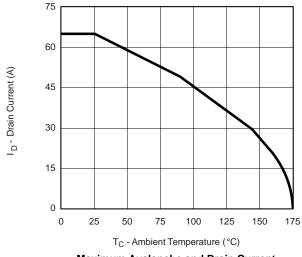
Source-Drain Diode Forward Voltage



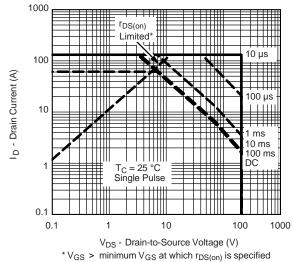
Drain Source Breakdown vs. Junction Temperature

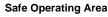


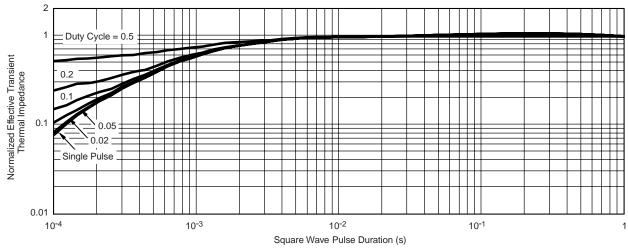
THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



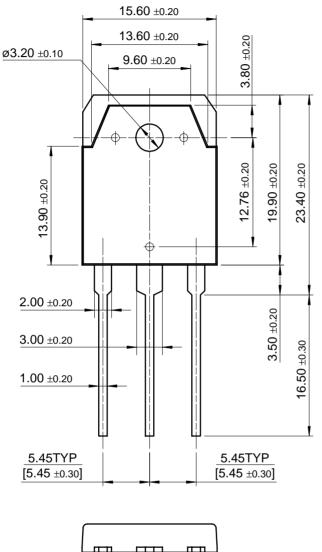


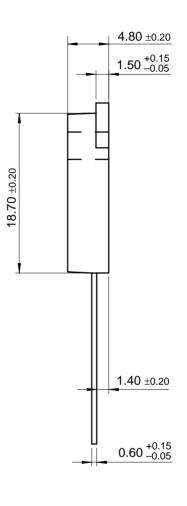


Normalized Thermal Transient Impedance, Junction-to-Case



TO-3P







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